



BT134-600D

## 1. General description

Planar passivated very sensitive gate four quadrant triac in a SOT82 plastic package intended for use in general purpose bidirectional switching and phase control applications where high sensitivity is required in all four quadrants. This "series D" triac is intended to be interfaced directly to microcontrollers, logic integrated circuits and other low power gate trigger circuits.

## 2. Features and benefits

- Compact package
- Direct interfacing to logic level ICs
- Direct interfacing to low power gate drive circuits
- High blocking voltage capability
- Low holding current for low current loads and lowest EMI at commutation
- Planar passivated for voltage ruggedness and reliability
- Triggering in all four quadrants
- Very sensitive gate

## 3. Applications

- General purpose low power motor control
- Home appliances
- Industrial process control

## 4. Quick reference data

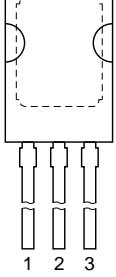
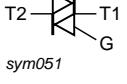
Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{DRM}$	repetitive peak off-state voltage		-	-	600	V
$I_{TSM}$	non-repetitive peak on-state current	full sine wave; $T_{j(init)} = 25 \text{ }^{\circ}\text{C}$ ; $t_p = 20 \text{ ms}$ ; <a href="#">Fig. 4</a> ; <a href="#">Fig. 5</a>	-	-	25	A
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{mb} \leq 107 \text{ }^{\circ}\text{C}$ ; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>	-	-	4	A
Static characteristics						
$I_{GT}$	gate trigger current	$V_D = 12 \text{ V}$ ; $I_T = 0.1 \text{ A}$ ; T2+ G+; $T_j = 25 \text{ }^{\circ}\text{C}$ ; <a href="#">Fig. 7</a>		-	2	5 mA

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
		$V_D = 12 \text{ V}$ ; $I_T = 0.1 \text{ A}$ ; T2+ G-; $T_j = 25^\circ\text{C}$ ; <a href="#">Fig. 7</a>		-	2.5	5	mA
		$V_D = 12 \text{ V}$ ; $I_T = 0.1 \text{ A}$ ; T2- G-; $T_j = 25^\circ\text{C}$ ; <a href="#">Fig. 7</a>		-	2.5	5	mA
		$V_D = 12 \text{ V}$ ; $I_T = 0.1 \text{ A}$ ; T2- G+; $T_j = 25^\circ\text{C}$ ; <a href="#">Fig. 7</a>		-	5	10	mA
$I_H$	holding current	$V_D = 12 \text{ V}$ ; $T_j = 25^\circ\text{C}$ ; <a href="#">Fig. 9</a>		-	1.2	10	mA

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	T1	main terminal 1		
2	T2	main terminal 2		
3	G	gate		
mb	T2	mounting base; main terminal 2	 <b>SIP3 (SOT82)</b>	 <i>sym051</i>

## 6. Ordering information

Table 3. Ordering information

Type number	Package			Version
	Name	Description		
BT134-600D	SIP3	plastic single-ended package; 3 leads (in-line)		SOT82

## 7. Limiting values

**Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
$V_{DRM}$	repetitive peak off-state voltage			-	600	V
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{mb} \leq 107^\circ\text{C}$ ; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>		-	4	A
$I_{TSM}$	non-repetitive peak on-state current	full sine wave; $T_{j(\text{init})} = 25^\circ\text{C}$ ; $t_p = 20\text{ ms}$ ; <a href="#">Fig. 4</a> ; <a href="#">Fig. 5</a>		-	25	A
		full sine wave; $T_{j(\text{init})} = 25^\circ\text{C}$ ; $t_p = 16.7\text{ ms}$		-	27	A
$I^2t$	$I^2t$ for fusing	$t_p = 10\text{ ms}$ ; SIN		-	3.1	$\text{A}^2\text{s}$
$dI_T/dt$	rate of rise of on-state current	$I_T = 6\text{ A}$ ; $I_G = 0.2\text{ A}$ ; $dI_G/dt = 0.2\text{ A}/\mu\text{s}$ ; T2+ G+		-	50	$\text{A}/\mu\text{s}$
		$I_T = 6\text{ A}$ ; $I_G = 0.2\text{ A}$ ; $dI_G/dt = 0.2\text{ A}/\mu\text{s}$ ; T2+ G-		-	50	$\text{A}/\mu\text{s}$
		$I_T = 6\text{ A}$ ; $I_G = 0.2\text{ A}$ ; $dI_G/dt = 0.2\text{ A}/\mu\text{s}$ ; T2- G-		-	50	$\text{A}/\mu\text{s}$
		$I_T = 6\text{ A}$ ; $I_G = 0.2\text{ A}$ ; $dI_G/dt = 0.2\text{ A}/\mu\text{s}$ ; T2- G+		-	10	$\text{A}/\mu\text{s}$
$I_{GM}$	peak gate current			-	2	A
$P_{GM}$	peak gate power			-	5	W
$P_{G(AV)}$	average gate power	over any 20 ms period		-	0.5	W
$T_{stg}$	storage temperature			-40	150	$^\circ\text{C}$
$T_j$	junction temperature			-	125	$^\circ\text{C}$

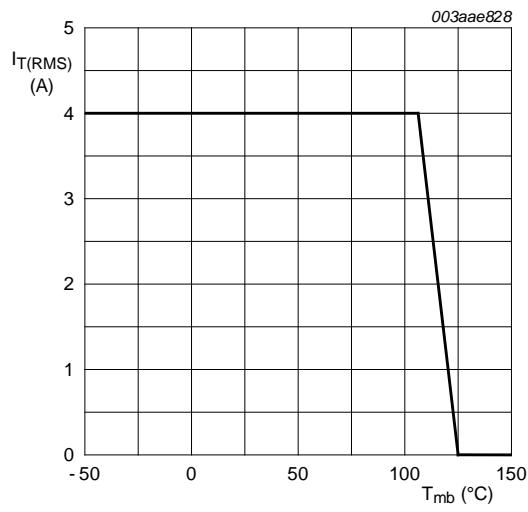
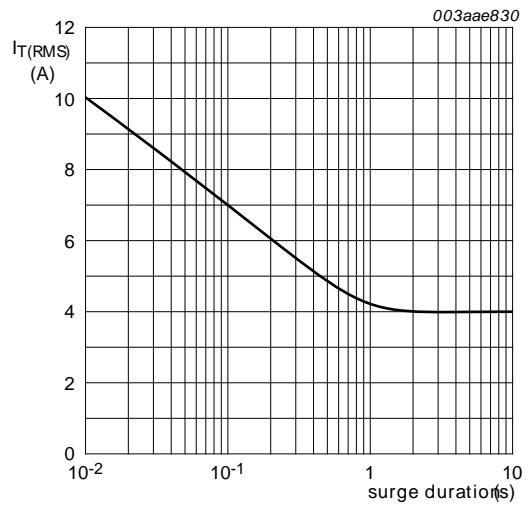


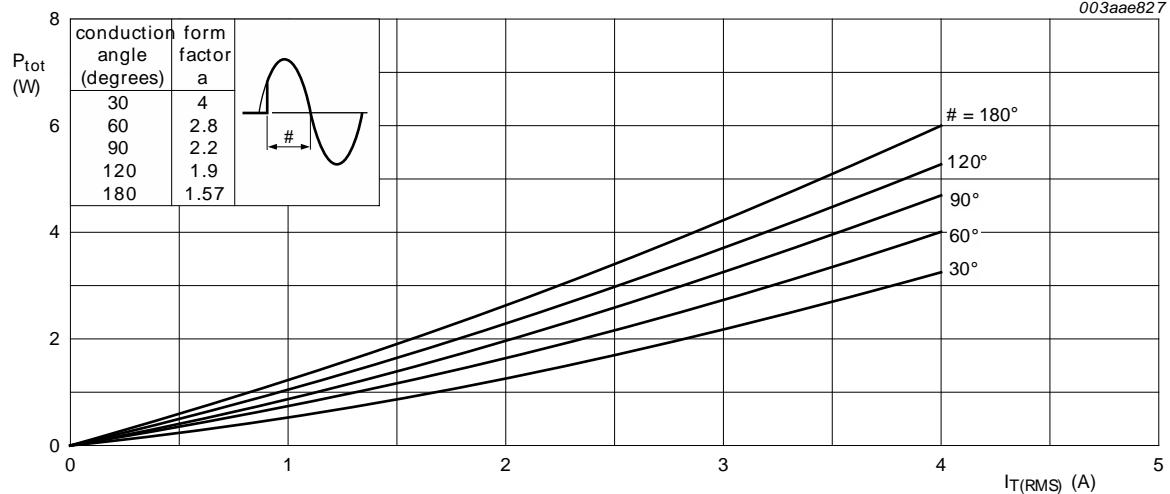
Fig. 1. RMS on-state current as a function of mounting base temperature; maximum values



f = 50 Hz

T<sub>mb</sub> ≤ 107 °C

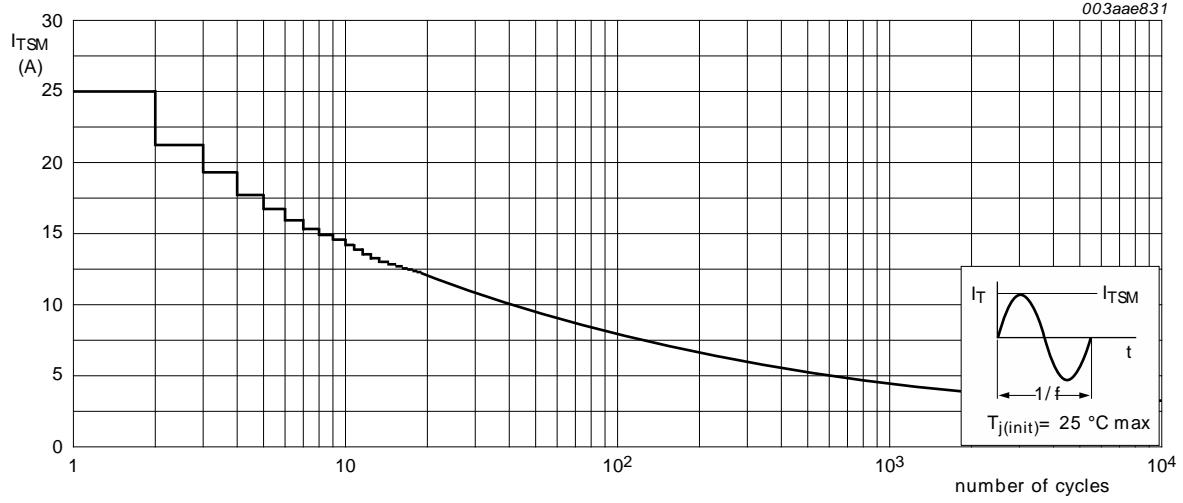
Fig. 2. RMS on-state current as a function of surge duration; maximum values



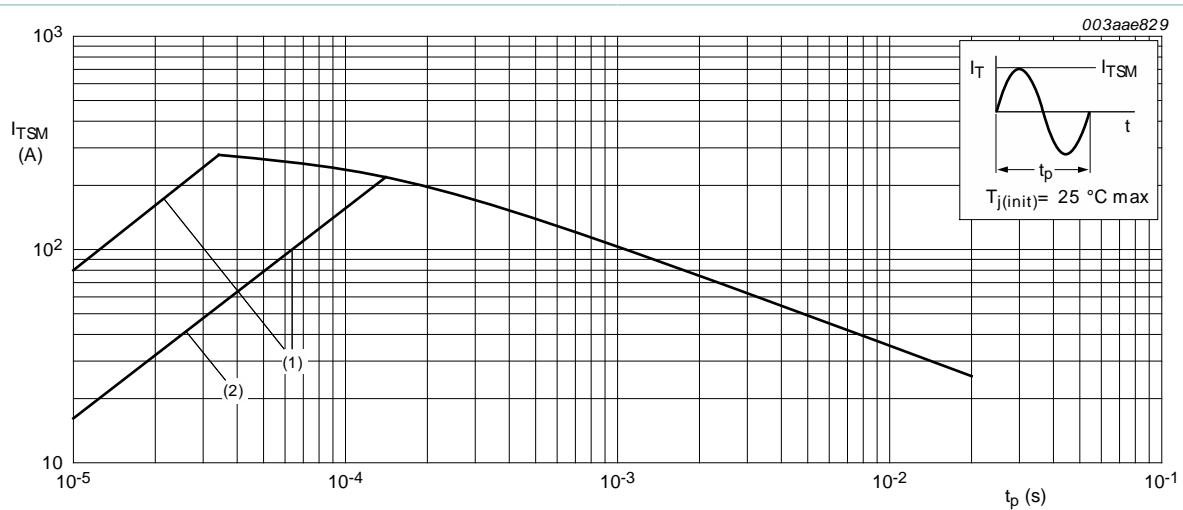
α = conduction angle

a = form factor = I<sub>T(RMS)</sub> / I<sub>T(AV)</sub>

Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values



**Fig. 4.** Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values

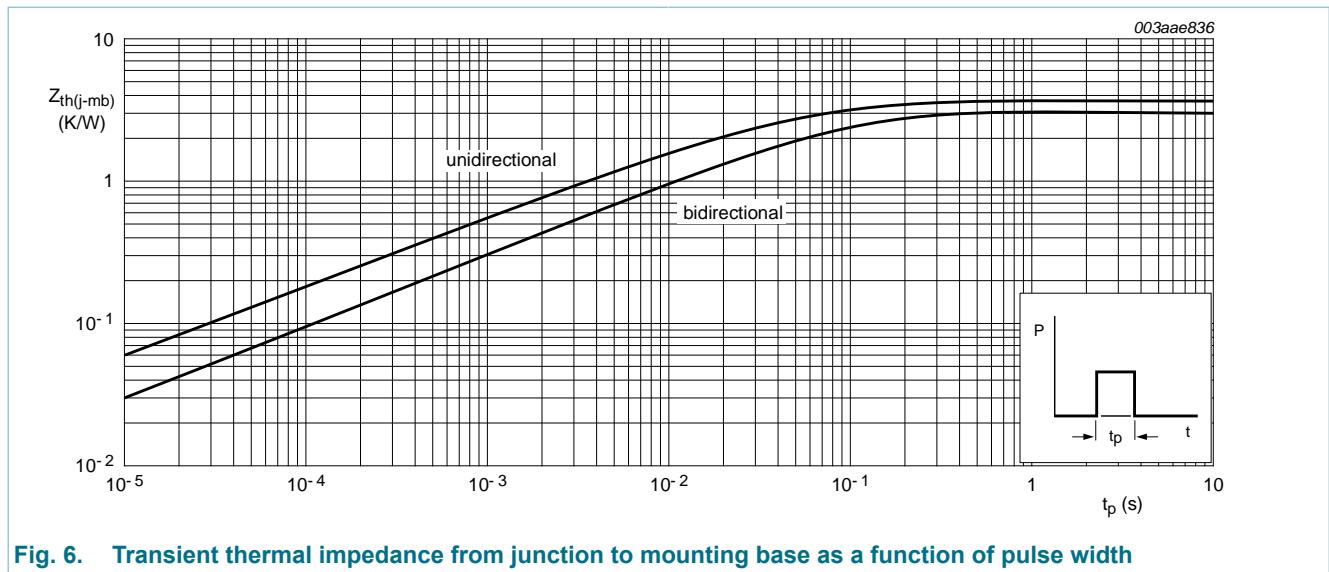


**Fig. 5.** Non-repetitive peak on-state current as a function of pulse width; maximum values

## 8. Thermal characteristics

**Table 5. Thermal characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j\text{-}mb)}$	thermal resistance from junction to mounting base	half cycle; <a href="#">Fig. 6</a>	-	-	3.7	K/W
		full cycle; <a href="#">Fig. 6</a>	-	-	3	K/W
$R_{th(j\text{-}a)}$	thermal resistance from junction to ambient	in free air	-	100	-	K/W

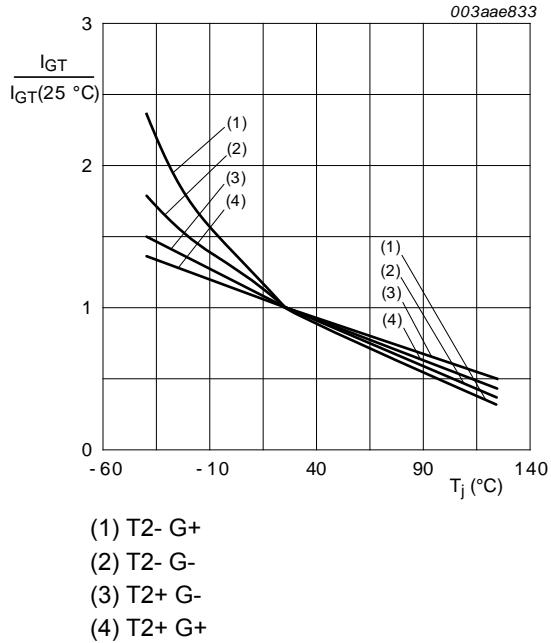


**Fig. 6. Transient thermal impedance from junction to mounting base as a function of pulse width**

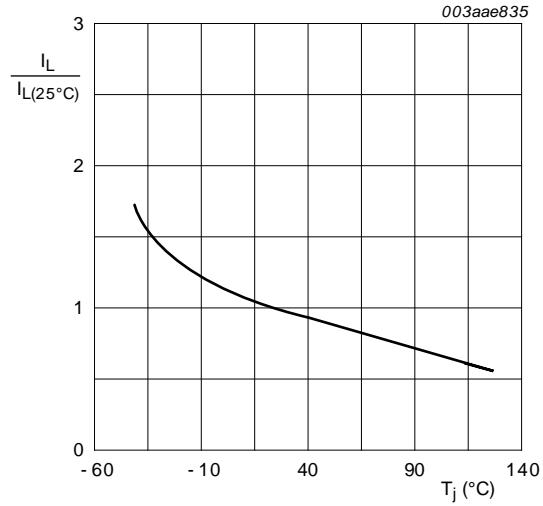
## 9. Characteristics

**Table 6. Characteristics**

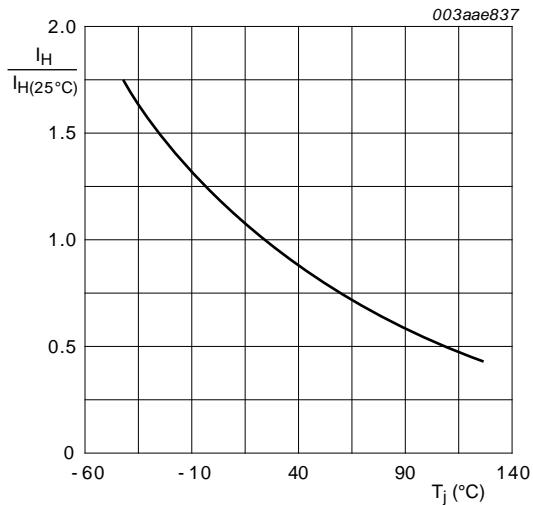
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
<b>Static characteristics</b>							
I <sub>GT</sub>	gate trigger current	V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2+ G+; T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>		-	2	5	mA
		V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2+ G-; T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>		-	2.5	5	mA
		V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2- G-; T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>		-	2.5	5	mA
		V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2- G+; T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>		-	5	10	mA
I <sub>L</sub>	latching current	V <sub>D</sub> = 12 V; I <sub>G</sub> = 0.1 A; T2+ G+; T <sub>j</sub> = 25 °C; <a href="#">Fig. 8</a>		-	1.6	10	mA
		V <sub>D</sub> = 12 V; I <sub>G</sub> = 0.1 A; T2+ G-; T <sub>j</sub> = 25 °C; <a href="#">Fig. 8</a>		-	4.5	15	mA
		V <sub>D</sub> = 12 V; I <sub>G</sub> = 0.1 A; T2- G-; T <sub>j</sub> = 25 °C; <a href="#">Fig. 8</a>		-	1.2	10	mA
		V <sub>D</sub> = 12 V; I <sub>G</sub> = 0.1 A; T2- G+; T <sub>j</sub> = 25 °C; <a href="#">Fig. 8</a>		-	2.2	15	mA
I <sub>H</sub>	holding current	V <sub>D</sub> = 12 V; T <sub>j</sub> = 25 °C; <a href="#">Fig. 9</a>		-	1.2	10	mA
V <sub>T</sub>	on-state voltage	I <sub>T</sub> = 5 A; T <sub>j</sub> = 25 °C; <a href="#">Fig. 10</a>		-	1.4	1.7	V
V <sub>GT</sub>	gate trigger voltage	V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T <sub>j</sub> = 25 °C; <a href="#">Fig. 11</a>		-	0.7	1	V
		V <sub>D</sub> = 400 V; I <sub>T</sub> = 0.1 A; T <sub>j</sub> = 125 °C; <a href="#">Fig. 11</a>		0.25	0.4	-	V
I <sub>D</sub>	off-state current	V <sub>D</sub> = 600 V; T <sub>j</sub> = 125 °C		-	0.1	0.5	mA
<b>Dynamic characteristics</b>							
dV <sub>D</sub> /dt	rate of rise of off-state voltage	V <sub>DM</sub> = 402 V; T <sub>j</sub> = 125 °C; R <sub>GT1</sub> = 1 kΩ; (V <sub>DM</sub> = 67% of V <sub>DRM</sub> ); exponential waveform		-	5	-	V/μs
t <sub>gt</sub>	gate-controlled turn-on time	I <sub>TM</sub> = 6 A; V <sub>D</sub> = 600 V; I <sub>G</sub> = 0.1 A; dI <sub>G</sub> / dt = 5 A/μs		-	2	-	μs



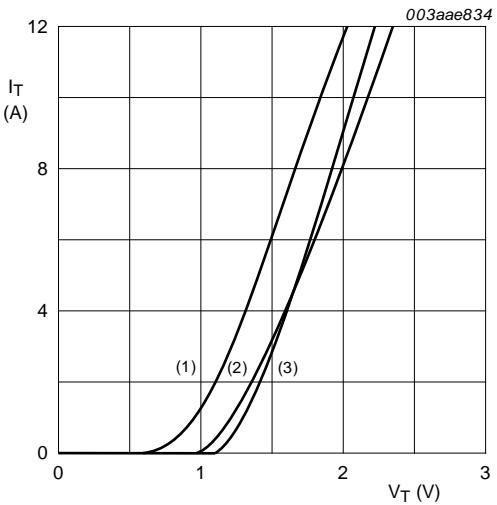
**Fig. 7.** Normalized gate trigger current as a function of junction temperature



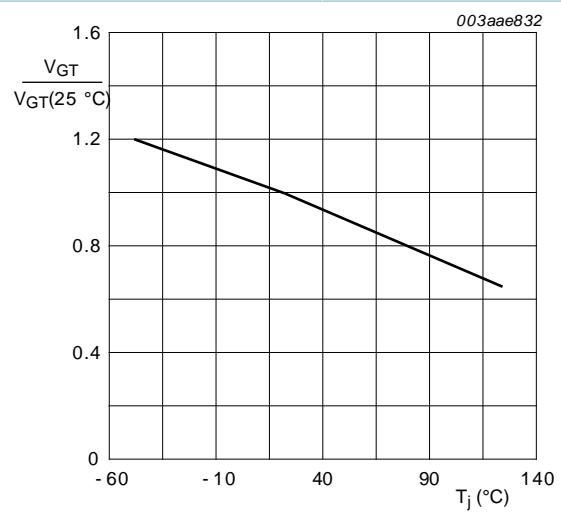
**Fig. 8.** Normalized latching current as a function of junction temperature



**Fig. 9.** Normalized holding current as a function of junction temperature



**Fig. 10.** On-state current as a function of on-state voltage

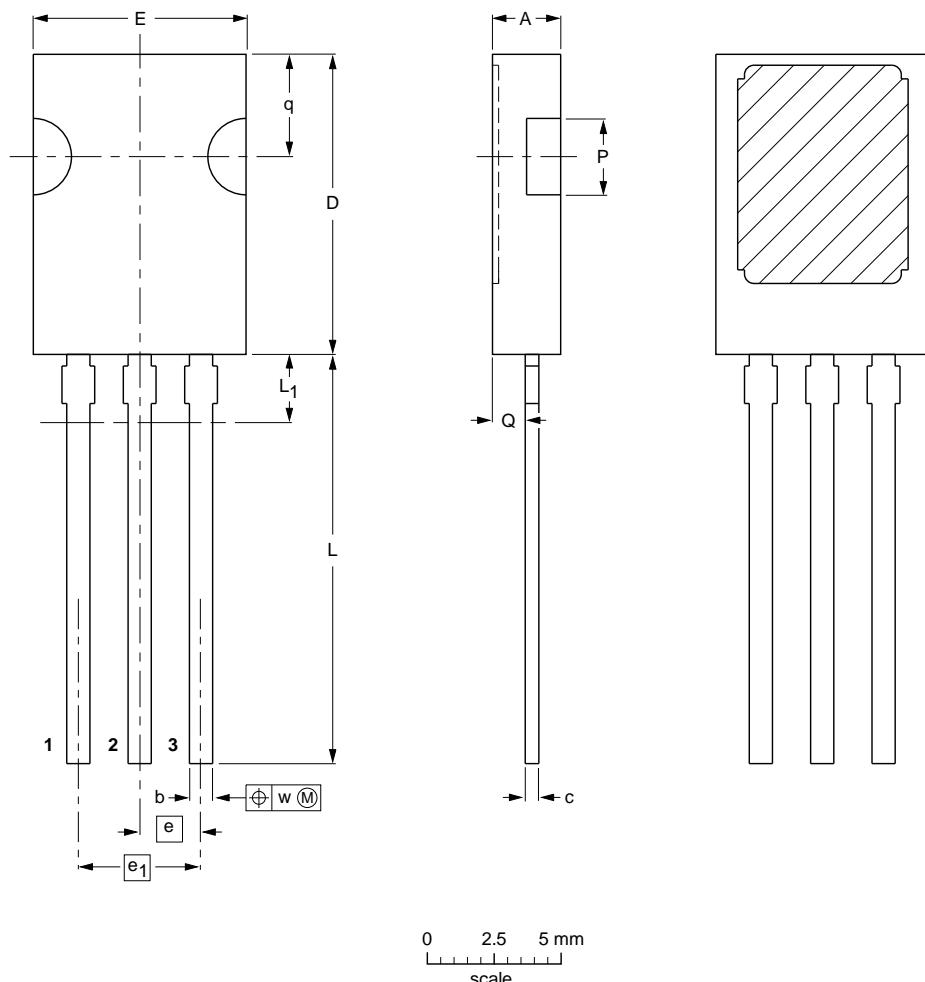


**Fig. 11.** Normalized gate trigger voltage as a function of junction temperature

## 10. Package outline

Plastic single-ended package; 3 leads (in-line)

SOT82



### DIMENSIONS (mm are the original dimensions)

UNIT	A	b	c	D	E	e	e <sub>1</sub>	L	L <sub>1</sub> <sup>(1)</sup> max.	P	Q	q	w
mm	2.8 2.3	0.88 0.65	0.58 0.47	11.1 10.5	7.8 7.2	2.29	4.58	16.5 15.3	2.54	3.1 2.5	1.5 0.9	3.9 3.5	0.254

### Note

1. Terminal dimensions within this zone are uncontrolled to allow for body and terminal irregularities.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT82						97-06-11

Fig. 12. Package outline SIP3 (SOT82)